

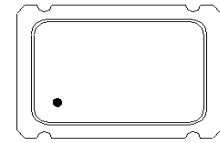
Features:

- Surface Mount Seam Weld Package
- Excellent Reliability Performance
- Good Frequency Perturbation and Stability over temperature
- Moisture Sensitivity Level (MSL) : Level-1

Application:

- Supply Voltage CMOS Output
- Option-able stand-by function for output .

2.048000 MHz
Crystal Oscillator



SM7050-4

Electrical Characteristics:

XO9024B	Specifications
Nominal Frequency, Fo	2.048000 MHz
Storage Temperature Range	-55°C to +125°C
Operating Temperature Range	-40°C to +85°C
Power Supply Voltage, Vcc	3.3 V +/- 10%
Load	15 pF
“0” Level “1” Level	Vol: 10%Vcc max Voh:90%Vcc min
Power Supply Current, Icc	20 mA max
Frequency Accuracy ¹	+/-25 ppm max
Duty Cycle	45% ~ 55%
Rise Time (10% -> 90% of final RF level in Vp-p) Fall Time (90% -> 10% of final RF level in Vp-p)	6 nsec max. 6 nsec max.
Star-up Time	10 msec max
Aging	+/-2.0 ppm/year
Enable/Disable Function	PIN 1: Vih:70%Vcc min or Open, PIN 3: Output Enable PIN 1: Vil:30%Vcc max, PIN 3:Output Disable

#Note 1: Frequency accuracy includes 25C tolerance, operating temperature range -40 to 85 deg C, aging and voltage or load change

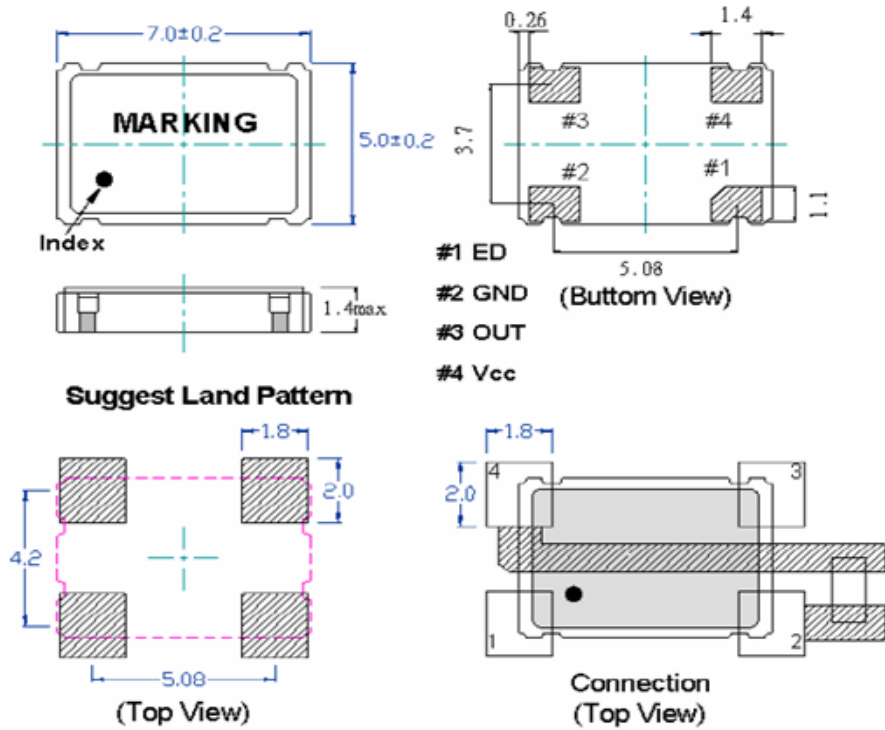


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

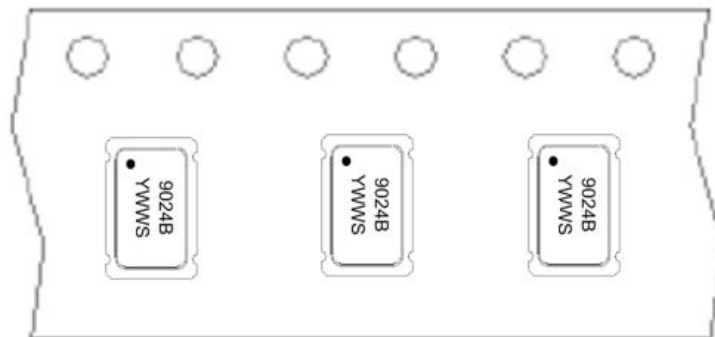
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Mechanical Dimensions: (Unit: mm)



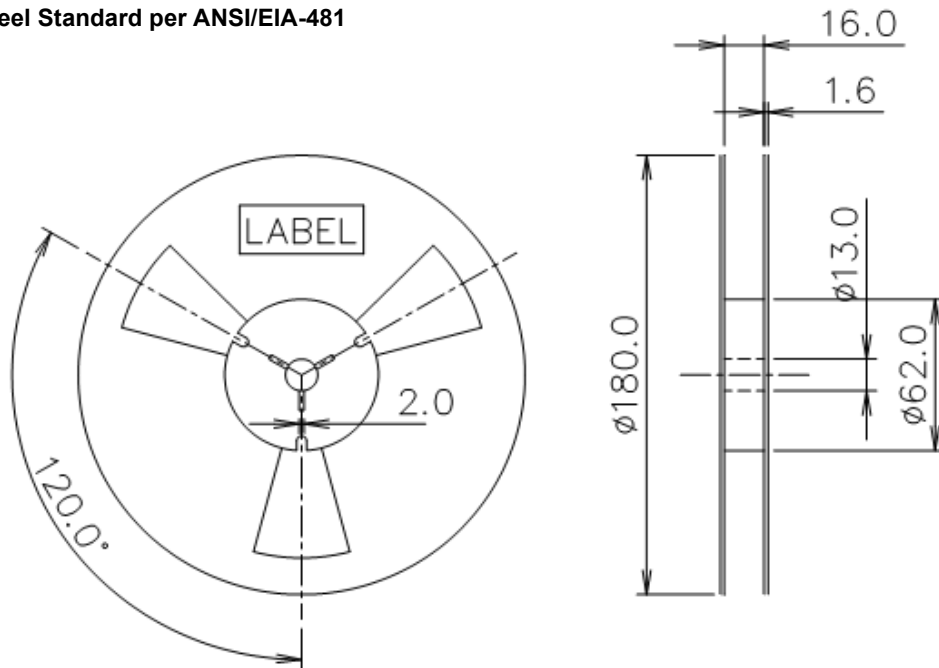
Marking:

Y = Year, WW = Week, S = Shift

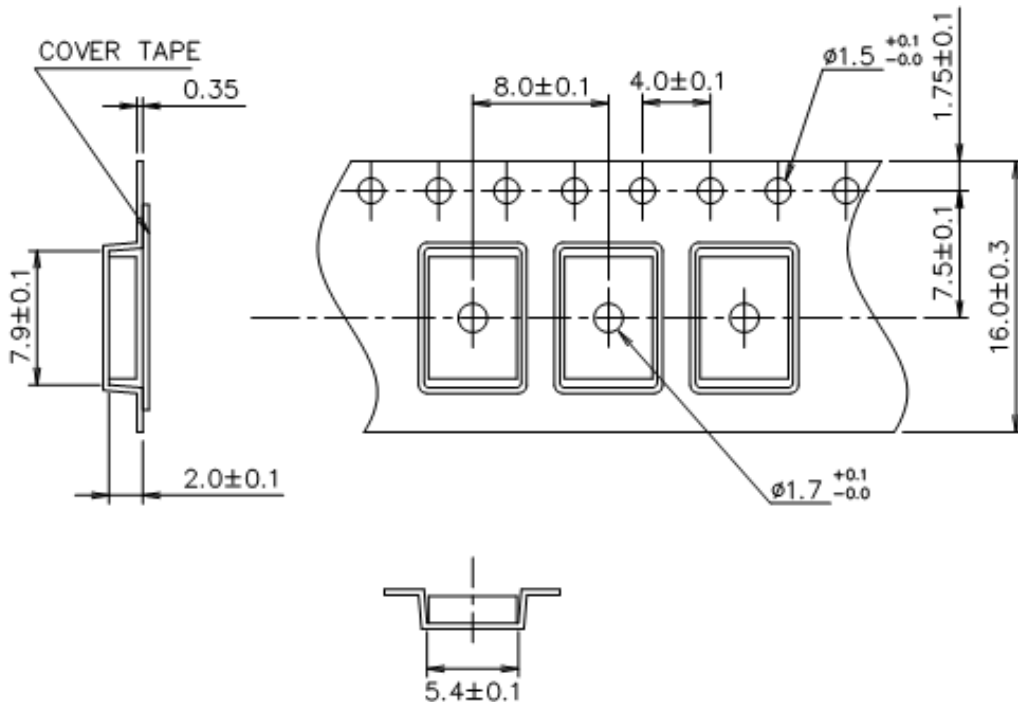


Reel Dimensions (mm): 7" reel count = 1000

Tape and Reel Standard per ANSI/EIA-481



Tape Dimensions (mm):

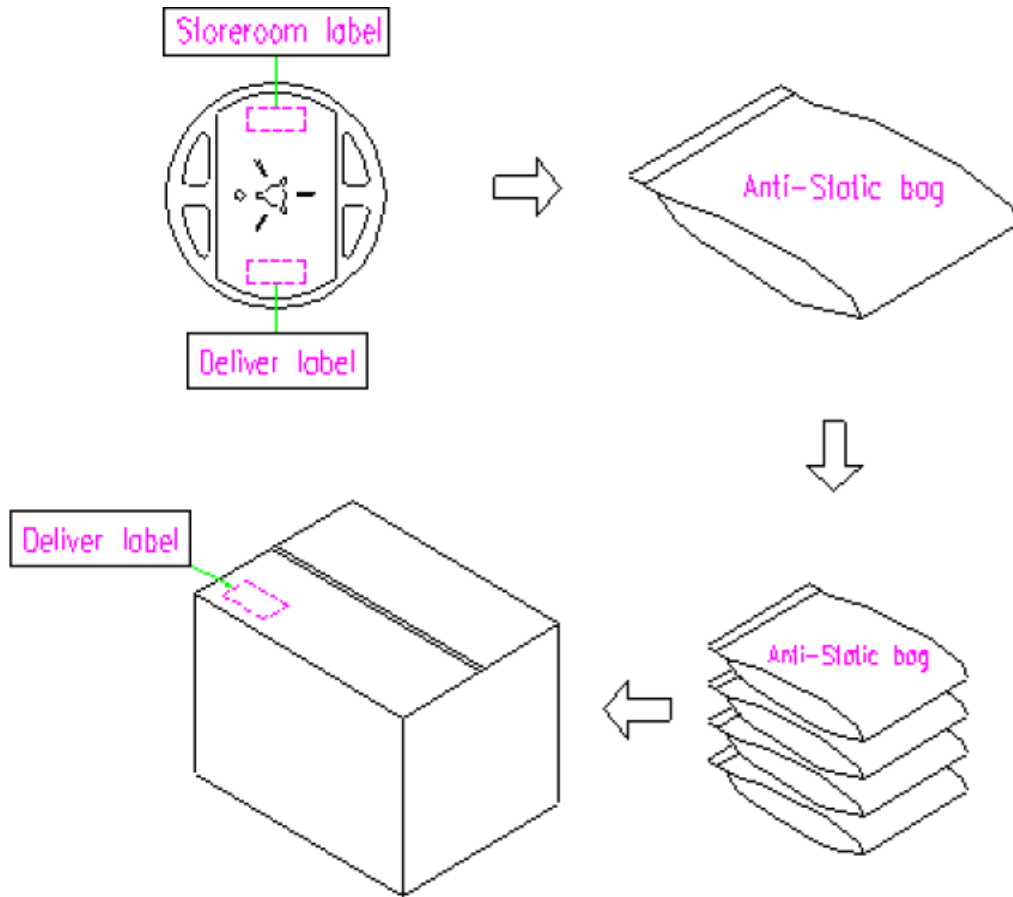


[NOTE]:

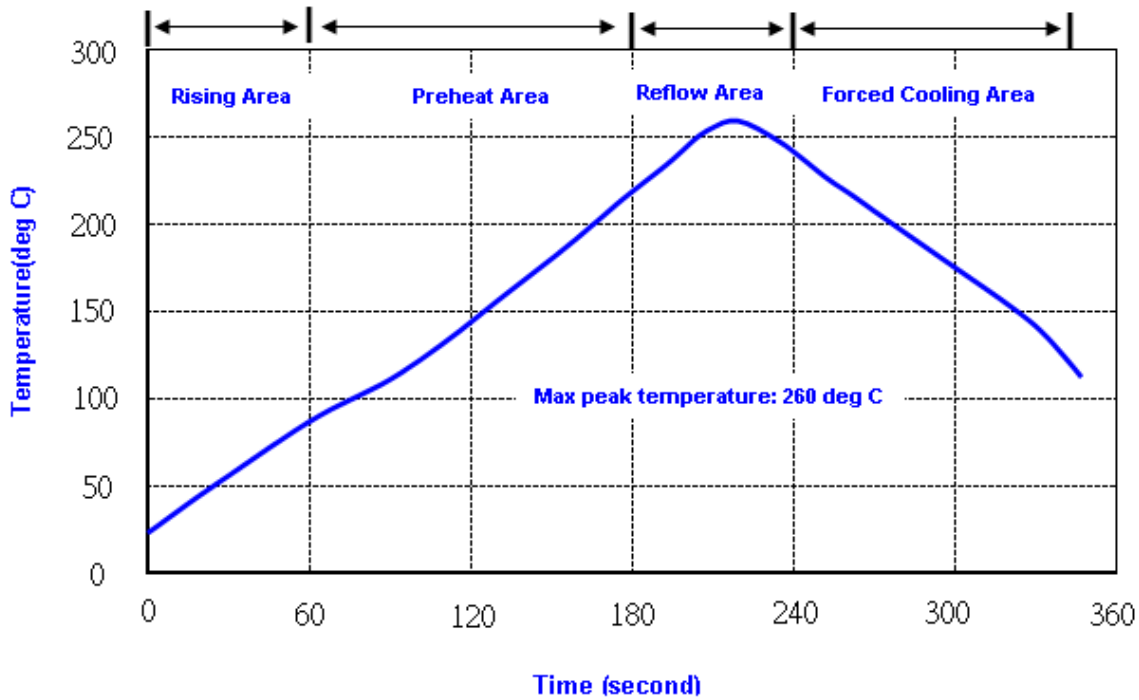
1. Unless otherwise specified tolerance on dimension +/-0.1 mm.
2. Material: conductive polystyrene with color black
3. 10 pitch cumulative tolerance +/-0.2 mm.
4. Packing Direction: dot or the logo of marking should be close to the hole of tape.

Packing Quantity/Packing:

1K pcs maximum per reel



Reflow Profile:



- Note:**
1. Max peak temperature: 260 \pm 5 deg C; Time: 10 \pm 2 sec
 2. Temperature: 217 \pm 5 deg C; Time: 90~100 sec

Reliability Specifications

Test name	Test process / method	Reference standard
Mechanical characteristics		
resistance to Soldering heat (IR reflow)	Temp./ Duration : 265°C /10sec ×2 times Total time : 4min.(IR-reflow)	EIAJED-4701 -300(301)M(II)
Vibration	Total peak amplitude : 1.5mm Vibration frequency : 10 to 2000 Hz Sweep period : 20 minute Vibration directions : 3 mutually perpendicular Duration : 2 hr / direc.	MIL-STD 202G method 204
Mechanical Shock	directions : 3 impacts per axis Acceleration : 3000g's, +20/-0 % Duration : 0.3 ms (total 18 shocks) Waveform : Half-sine	MIL-STD 202G method 213
Solderability	Solder Temperature:265±5°C Duration time: 5±0.5 seconds.	J-STD-002
Environmental characteristics		
Thermal Shock	Heat cycle conditions -40 °C (30min) ↔ 85 °C (30min) * cycle time : 10 times	MIL-STD 883G method 1010.8
Humidity test	Temperature : 85 ± 2 °C Relative humidity : 85% Duration : 96 hours	MIL-STD 202G method 103
Dry heat (Aging test)	Temperature : 125 ± 2 °C Duration : 168 hours	MIL-STD 202G method 108A
Cold resistance (Low Temp Storage)	Temperature : -40 ± 2 °C Duration : 96 hours	IEC 60068-2-1